



The Adherent AI Technology's Newsletter

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Greetings,

Welcome to The Adherent Newsletter. Your source for new products and innovations from AIT. AI Technology has been hard at work designing new materials to meet the ever increasing needs of today's electronics manufacturers. We hope we can help with your application.



AIT at Semicon West - Booth 617

AI Technology, Inc. will once again be exhibiting at Semicon West next week in beautiful San Francisco. The show will run from July 14th through the 16th



at Moscone Center and AIT will be at booth 617. This year AIT will be displaying our new Dicing Die Attach Film (DDAF), Cool Clad Insulated Metal Substrate, and will have knowledgeable staff on site to discuss our extensive line of adhesive and thermally conductive films and pastes.

Please stop by and see us. If you can't make the show visit our website @ www.aitechnology.com or give us a call 609-799-9388

See full list of upcoming shows

AMBIENT CURE EPOXIES



AIT has had many requests for a good, ambient-cure epoxy that can meet the demands of the electronic industry.

The requirements for this epoxy are typical of other high-temperature cure epoxies currently being used for die-attach, substrate-attach, lid-seal, conformal coatings, etc.

There are various areas where an ambient cure epoxy will be used: space, medical, automotive, defense, commercial and others. The sensitivity to heat for MEMs, Optical and other applications make an Ambient-Cure epoxy a necessity for many electronic packaging applications. High pressure normally required for some epoxies to form a strong bond are not required for this new ambient-cure epoxy. This allows many pressure-sensitive devices, to use our epoxy for assembly.

The two products currently being offered by AIT are electrically insulating with high thermal conductivity. AIT is currently working on an Electrically Conductive version as well.

They are 2-part epoxies that when mixed, will cure into an epoxy that will meet most requirements in this industry.

Please contact AI Technology for more information on our ROOM-TEMP cure epoxies!

Application Analysis Form

AIT Thermal Gap Pads

AIT has long been known for our thermally conductive gap filling pads. These thermal pads can be used to eliminate air gaps to increase thermal conductivity.

AIT's pads are made with a silicone free chemistry and provide electrical isolation with thermal conductivities up to 4w/mk. These conformable pads can easily bridge the gap between uneven and textured surfaces without adding stress to sensitive components.

AIT also offers silver filled electrically conductive pads that offer improved thermal conductivity, over 9w/mk, and provide the added benefit of electrical grounding.

AIT manufactures all of our materials to your precise specifications. We offer tacky or tack free variations to meet your processing requirements. These pads are made to the custom thickness you need and can be precut into performs to speed your production line.

See more about these products

Let AIT solve your problem

Sincerely,

AI Technology

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